

PCB Production Process Technology Explain

1. Common Info



1.0 Main Linkman: 丁朝阳 Phone: 13927497578
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 1.1 Other linkmen: 戴康明 Phone: 13714646123 E-mail: kangming.dai@hanputek.com
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 Please send EQ confirming order to main linkman, and copy to all others!

2. Technology Information

2.0 Board Name: CRD30DD12N-K_30K_RevC Board Type: Common Rigid Board
 2.1 Layer Count: 4 Layers Min Via Stagger (mm): 0.3048
 2.2 Base Material: FR4 Via Density (one/square metre): 98829.88
 2.3 Aspect Ratio: 5:1 Min. Line Width/Spacing (mil): 5.00/3.00
 Warpage: <=0.75%
 2.4 Unit Size (mm): 100.00 X 55.00 Panel Mode: 2 X 5
 Set Size (mm): 202.00 X 275.00 Cell Count: 10 Single board types of panel: 1
☒ V-CUT
 2.5 Board Thickness (mm): 1.6 Tolerance: $\pm 10\%$
 2.6 Soldermask: both sides Color: Green Mill Finish: Polished
 2.7 Refdes: both sides Color: White
 Mark: ☐ UL
 Don not put factory logo in the blank space of this board.
 Please put manufacturing date in the blank space of this board.
 2.8 Surface Finish: Lead Free HAL Tin Thick: 1-40um Gold Finger: ☒ No ☐ Yes, Gold Thick:
 Gold Finger Bevel: ☐ Yes ☒ No
 Cut Thin: ☐ Yes ☒ No
 2.9 Via Soldermask Dispose Process: ☐ All vias should be plugged except the vias on pad
☐ All vias according to design ☒ All vias need to be plugged.
☐ Vias under BGA should be plugged, Other vias according to design Stuff matter: Printing ink
 2.10 Impedance Control: ☐ Yes ☒ No
 2.11 HDI: ☐ Yes ☒ No
 2.12 Inspection & Acceptance Criteria: ☒ IPC-6012-II, current revision.
 2.13 IPC Netlist Comparison: ☒ Yes ☐ No
 2.14 Delivery Accessory: ☒ Electrical Test Report ☒ Deliver Test Report ☒ Gerber
☒ PCB Micro Section Report (Minimum Via & All Layers Copper Position)
☒ Impedance Test Report ☐ Other
 2.15 Package Requirements: ☒ Vacuum Package ☒ Fill In The Gap With Paper

3. Layer Stack Setup

REFERENCE LAYER STACKUP (Unit:mils)

1.60mm	49.80 mil	Core	→		←Layer1	TOP	1.40 mil	Copper+Plating
					←Layer2	ART02	1.40 mil	
					←Layer3	ART03	1.40 mil	
					←Layer4	BOTTOM	1.40 mil	Copper+Plating
	3.80 mil	Prepreg	→					
	3.80 mil	Prepreg	→	